To the Honorable Commissioner

1. Name of conveying party(ies):
   Jae-Hyun YEO, Young-Wook Park,
   Ki-Chul KIM, Jae-Jong HAN

Additional name(s) of conveying party(ies) attached? □ Yes □ No

2. Name and address of receiving party(ies):
   Name: SAMSUNG ELECTRONICS CO., LTD.
   Internal Address: 416, Maetan-dong,
   Yeongtong-gu, Suwon-si, Gyeonggi-do,
   Republic of Korea

Additional name(s) & address(es) attached: □ Yes □ No

3. Nature of conveyance:
   □ Assignment □ Merger
   □ Security Agreement □ Change of Name
   □ Other
   Execution Date: January 17, 2005 (JHY, YWP, KCK) and January 18, 2005 (JJH)

4. Application number(s) or patent number(s):
   If this document is being filed together with a new application, the execution date
   of the application is: January 17, 2005 (JHY, YWP, KCK) and January 18, 2005 (JJH)

   A. Patent Application No.(s)
   B. Patent No.(s)

   Additional numbers attached? □ Yes □ No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: Frank Chau, Esq.
   Street Address: F. CHAU & ASSOCIATES, LLC
   1900 Hempstead Turnpike, Suite 501
   City: East Meadow, State: NY, Zip: 11554
   01/26/2005 HLE333 00000064 11038324
   05 FC8021 40.00 00

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): $40.00
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   □ Authorized to be charged to deposit account

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PATENT
REEL: 016201 FRAME: 0890
AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that:  
IN CONSIDERATION of the sum of TEN ($10.00) dollars or the equivalent thereof, and other good 
and valuable consideration, the receipt of which from the hereinafter named Assignee is hereby 
acknowledged, I do hereby sell, assign and forever grant and convey unto:

ASSIGNEE: Samsung Electronics Co., Ltd.

ADDRESS: 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, KOREA

Who is my Assignee, and to the successes and assigns of my Assignee, all my right, title 
and interest, in and for the United States of America and all other countries, including all rights of 
priority, in and to the invention entitled:

TITLE: METHOD OF FORMING THIN FILM FOR SEMICONDUCTOR DEVICE AND 
APPARATUS THEREFOR

invented by me (if only one inventor is named below) or us (if more than one inventor is named 
below) and described in an application for a United States patent the specification of which is either 
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and in and to all United States patents which may be granted thereon and therefore, and in and to 
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patent when granted, to be held and enjoyed by said SAMSUNG ELECTRONICS CO., LTD., my 
Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or 
any extension or renewal thereof, for which said patent or patents may be granted, as fully and 
entirely as the same would have been held and enjoyed by me or us if this assignment, sale and 
conveyance had not been made;

AND I hereby covenant and agree to sign and execute any further documents or instruments 
which may from time-to-time be either necessary, lawful, proper or requested by the Assignee, in the 
prosecution of the above-named application or in the preparation and prosecution of any certificate 
of correction, division, continuation, continuation-in-part, reissue, re-examination, in any 
amendment, extension, or interference proceeding, whether administrative or judicial, or otherwise, 
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AND I do hereby authorize and request the Commissioner of Patents and Trademarks to 
issue said Patent or Patents to the Assignee, and I hereby appoint as my, or our attorney, and 
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I HEREBY DECLARE that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 1001 of Title 18 U.S. Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Date: 18 January, 2005

RECORDED: 01/19/2005
PATENT
REEL: 016201 FRAME: 0892